SLLS111B - SEPTEMBER 1980 - REVISED MAY 1995

- Meets or Exceeds the Requirements of ANSI Standards EIA/TIA-422-B and EIA/TIA-423-B and ITU Recommendations V.10 and V.11
- Operates From Single 5-V Power Supply
- Wide Common-Mode Voltage Range
- High Input Impedance
- TTL-Compatible Outputs
- High-Speed Schottky Circuitry
- 8-Pin Dual-in-Line and Small-Outline Packages
- Designed to Be Interchangeable With National DS9637A

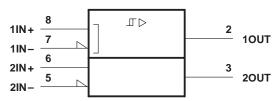
V_{CC} 1 8 1 1IN+ 1OUT 2 7 1 1IN2OUT 3 6 2INGND 4 5 2IN-

description

The uA9637AC is a dual differential line receiver designed to meet ANSI Standards EIA/TIA-422-B and EIA/TIA-423-B and ITU Recommendations V.10 and V.11. The line receiver utilizes Schottky circuitry and has TTL-compatible outputs. The inputs are compatible with either a single-ended or a differential-line system. This device operates from a single 5-V power supply and is supplied in an 8-pin dual-in-line package or small-outline package.

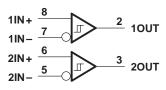
The uA9637AC is characterized for operation from 0°C to 70°C.

logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram

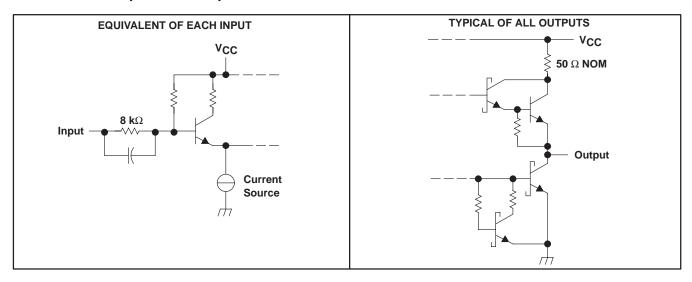




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schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} (see Note 1)	0.5 V to 7 V
Input voltage, V _I	±15 V
Differential input voltage, V _{ID} (see Note 2)	±15 V
Output voltage range, VO (see Note 1)	0.5 V to 5.5 V
Low-level output current, I _{OL}	50 mA
Continuous total dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range, T _{stq}	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds .	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential input voltage, are with respect to the network ground terminal.
 - 2. Differential input voltage is measured at the noninverting input with respect to the corresponding inverting input.

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{$A$}} \leq 25^{\circ}\mbox{$C$}$ POWER RATING	OPERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 125°C POWER RATING
D	725 mW	5.8 mW/°C	464 mW	_
Р	1000 mW	8.0 mW/°C	640 mW	_



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recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	4.75	5	5.25	V
Common-mode input voltage, V _{IC}			±7	V
Operating free-air temperature, TA	0		70	°C

electrical characteristics over recommended ranges of supply voltage, common-mode input voltage, and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CON	DITIONS	MIN	TYP†	MAX	UNIT
\/-	Positive-going input threshold voltage	See Note 3			0.2	V	
VIT+	Positive-going input threshold voltage	See Note 3				0.4	V
\/	Negative going input threehold valtage	See Note 3		-0.2			V
V _{IT} — Negative-going input threshold voltage		See Note 3	-0.4‡			V	
V _{hys}	Hysteresis voltage (V _{IT+} -V _{IT-})				70		mV
Vон	High-level output voltage	$V_{ID} = 0.2 V,$	$I_O = -1 \text{ mA}$	2.5	3.5		V
VOL	Low-level output voltage	$V_{ID} = -0.2 V$,	$I_O = 20 \text{ mA}$		0.35	0.5	V
1.	Input current	$V_{CC} = 0 \text{ to } 5.5 \text{ V},$	V _I = 10 V		1.1	3.25	mA
"	input current	See Note 4	$V_{I} = -10 \text{ V}$		-1.6	-3.25	IIIA
los	Short-circuit output current§	$V_{O} = 0,$	$V_{ID} = 0.2 V$	-40	-75	-100	mA
ICC	Supply current	$V_{ID} = -0.5 V$,	No load		35	50	mA

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t PLH	Propagation delay time, low- to high-level output	C _I = 30 pF. See Figure 1		15	25	ns
tPHL	Propagation delay time, high- to low-level output	CL = 50 pr, See Figure 1		13	25	ns



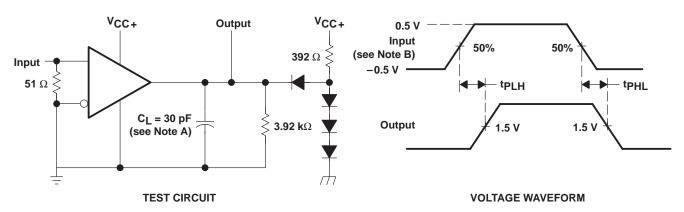
[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ The algebraic convention, in which the less positive (more negative) limit is designated as minimum, is used in this data sheet for threshold levels

[§] Only one output should be shorted at a time, and duration of the short circuit should not exceed one second.

NOTES: 3. The expanded threshold parameter is tested with a $500-\Omega$ resistor in series with each input.

^{4.} The input not under test is grounded.

PARAMETER MEASUREMENT INFORMATION

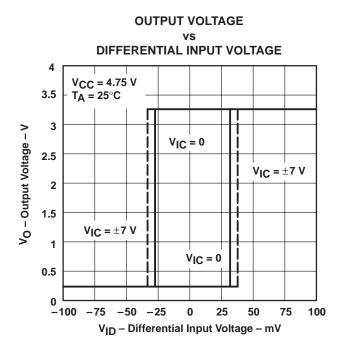


NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: $t_r \le 5$ ns, $t_f \le 5$ ns, $PRR \le 5$ MHz, duty cycle = 50%.

Figure 1. Test Circuit and Voltage Waveform

TYPICAL CHARACTERISTICS





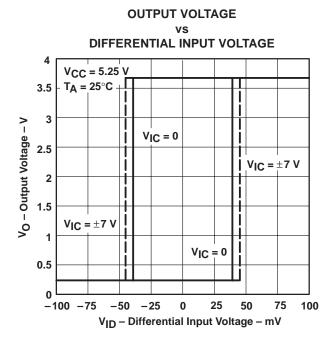
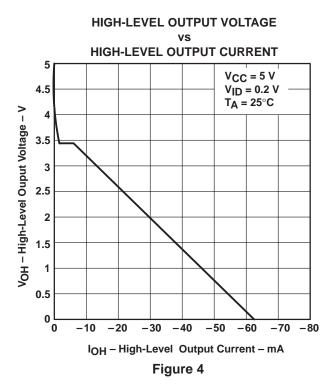
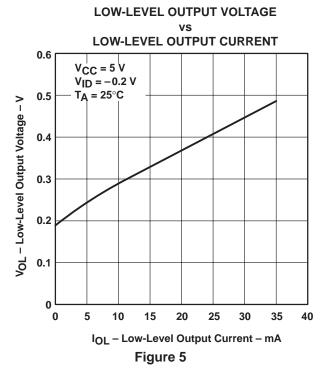


Figure 3

TYPICAL CHARACTERISTICS





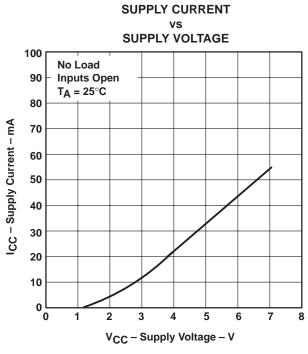




Figure 6

APPLICATION INFORMATION

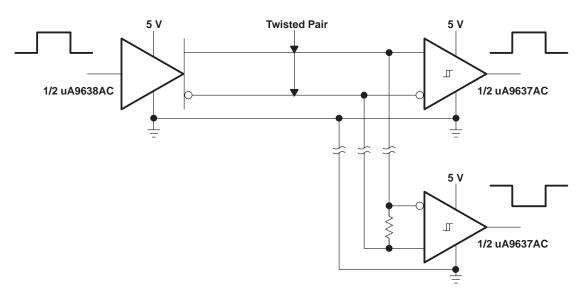


Figure 7. EIA/TIA-422-B System Applications







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
UA9637ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UA9637ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UA9637ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UA9637ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UA9637ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UA9637ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UA9637ACJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
UA9637ACP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
UA9637ACPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
UA9637ACPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
UA9637ACPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
UA9637ACPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM

4-Jun-2007

no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by Customer on an annual basis.



TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UA9637ACDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UA9637ACPSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UA9637ACDR	SOIC	D	8	2500	340.5	338.1	20.6
UA9637ACPSR	SO	PS	8	2000	346.0	346.0	33.0



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.



JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm

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